

# Low Voltage 4 $\Omega$ Quad SPST Switches

## ADG711/ADG712/ADG713

#### **FEATURES**

+1.8 V to +5.5 V Single Supply
Low On Resistance (2.5 Ω Typ)
Low On-Resistance Flatness
-3 dB Bandwidth > 200 MHz
Rail-to-Rail Operation
16-Lead TSSOP and SOIC Packages
Fast Switching Times

t<sub>ON</sub> 16 ns t<sub>OFF</sub> 10 ns Typical Power Consumption (< 0.01 μW) TTL/CMOS Compatible

APPLICATIONS
Battery Powered Systems
Communication Systems
Sample Hold Systems
Audio Signal Routing
Video Switching
Mechanical Reed Relay Replacement

#### **GENERAL DESCRIPTION**

The ADG711, ADG712 and ADG713 are monolithic CMOS devices containing four independently selectable switches. These switches are designed on an advanced submicron process that provides low power dissipation yet gives high switching speed, low on resistance, low leakage currents and high bandwidth.

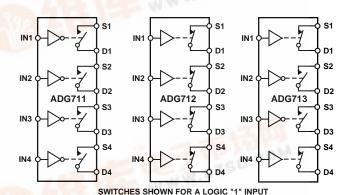
They are designed to operate from a single +1.8 V to +5.5 V supply, making them ideal for use in battery powered instruments and with the new generation of DACs and ADCs from Analog Devices. Fast switching times and high bandwidth make the part suitable for video signal switching.

The ADG711, ADG712 and ADG713 contain four independent single-pole/single throw (SPST) switches. The ADG711 and ADG712 differ only in that the digital control logic is inverted. The ADG711 switches are turned on with a logic low on the appropriate control input, while a logic high is required to turn on the switches of the ADG712. The ADG713 contains two switches whose digital control logic is similar to the ADG711, while the logic is inverted on the other two switches.

Each switch conducts equally well in both directions when ON. The ADG713 exhibits break-before-make switching action.

The ADG711/ADG712/ADG713 are available in 16-lead TSSOP and 16-lead SOIC packages.

#### FUNCTIONAL BLOCK DIAGRAMS



#### PRODUCT HIGHLIGHTS

- +1.8 V to +5.5 V Single Supply Operation. The ADG711, ADG712 and ADG713 offer high performance and are fully specified and guaranteed with +3 V and +5 V supply rails.
- 2. Very Low  $R_{ON}$  (4.5  $\Omega$  max at +5 V, 8  $\Omega$  max at +3 V). At supply voltage of +1.8 V,  $R_{ON}$  is typically 35  $\Omega$  over the temperature range.
- 3. Low On-Resistance Flatness.
- 4. −3 dB Bandwidth >200 MHz.
- Low Power Dissipation. CMOS construction ensures low power dissipation.
- 6. Fast t<sub>ON</sub>/t<sub>OFF</sub>.
- 7. Break-Before-Make Switching.
  This prevents channel shorting when the switches are configured as a multiplexer (ADG713 only).
- 8. 16-Lead TSSOP and 16-Lead SOIC Packages.

reliable. However, no responsibility is assumed by Analog Devices for its use nor for any infringements of patents or other rights of third parties which may result from its use. No license is granted by implication or

One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106, U.S.A. Tel: 781/329-4700 World Wide Web Site: http://www.analog.com

## $\label{eq:add_specifications} \textbf{ADG711/ADG712/ADG713} \\ -\textbf{SPECIFICATIONS}^{1~(V_{DD}~=~+5~V~\pm~10\%,~GND~=~0~V.~All~specifications} \\ -40^{\circ}\text{C}~to~+85^{\circ}\text{C}~unless~otherwise~noted.})$

	B Ve	ersion -40°C to		
Parameter	+25°C	+85°C	Units	Test Conditions/Comments
ANALOG SWITCH				
Analog Signal Range		$0 \text{ V to V}_{DD}$	V	
On-Resistance (R <sub>ON</sub> )	2.5	22	Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_S = -10 \text{ mA};$
	4	4.5	Ω max	Test Circuit 1
On-Resistance Match Between		0.05	Ω typ	$V_{\rm S} = 0 \text{ V to } V_{\rm DD}, I_{\rm S} = -10 \text{ mA}$
Channels ( $\Delta R_{ON}$ )		0.3	Ω max	
On-Resistance Flatness (R <sub>FLAT(ON)</sub> )	0.5		Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_S = -10 \text{ mA}$
		1.0	Ω max	
LEAKAGE CURRENTS				$V_{\rm DD} = +5.5 \text{ V};$
Source OFF Leakage I <sub>S</sub> (OFF)	±0.01		nA typ	$V_S = 4.5 \text{ V/1 V}, V_D = 1 \text{ V/4.5 V};$
	±0.1	$\pm 0.2$	nA max	Test Circuit 2
Drain OFF Leakage I <sub>D</sub> (OFF)	±0.01		nA typ	$V_S = 4.5 \text{ V/1 V}, V_D = 1 \text{ V/4.5 V};$
	±0.1	$\pm 0.2$	nA max	Test Circuit 2
Channel ON Leakage ID, IS (ON)	±0.01		nA typ	$V_S = V_D = 1 \text{ V, or } 4.5 \text{ V;}$
	±0.1	$\pm 0.2$	nA max	Test Circuit 3
DIGITAL INPUTS				
Input High Voltage, V <sub>INH</sub>		2.4	V min	
Input Low Voltage, V <sub>INI</sub>		0.8	V max	
Input Current				
I <sub>INL</sub> or I <sub>INH</sub>	0.005		μA typ	$V_{IN} = V_{INL}$ or $V_{INH}$
		$\pm 0.1$	μA max	
DYNAMIC CHARACTERISTICS <sup>2</sup>				
$t_{ON}$	11		ns typ	$R_L = 300 \Omega, C_L = 35 pF,$
		16	ns max	$V_S = 3 \text{ V}$ ; Test Circuit 4
$t_{ m OFF}$	6		ns typ	$R_L = 300 \Omega, C_L = 35 pF,$
		10	ns max	$V_S = 3 V$ ; Test Circuit 4
Break-Before-Make Time Delay, t <sub>D</sub>	6		ns typ	$R_L = 300 \Omega, C_L = 35 pF,$
(ADG713 Only)		1	ns min	$V_{S1} = V_{S2} = 3 \text{ V}$ ; Test Circuit 5
Charge Injection	3		pC typ	$V_S = 2 V; R_S = 0 \Omega, C_L = 1 nF;$
				Test Circuit 6
Off Isolation	-58		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 10 MHz$
	-78		dB typ	$R_L = 50 \Omega, C_L = 5 pF, f = 1 MHz;$
				Test Circuit 7
Channel-to-Channel Crosstalk	<del>-90</del>		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 10 MHz$ ; Test Circuit 8
Bandwidth -3 dB	200		MHz typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ ; Test Circuit 9
$C_{S}$ (OFF)	10		pF typ	_
$C_D$ (OFF)	10		pF typ	
$C_D, C_S(ON)$	22		pF typ	
POWER REQUIREMENTS				V <sub>DD</sub> = +5.5 V
$I_{ m DD}$	0.001		μA typ	Digital Inputs = 0 V or 5 V
		1.0	μA max	

NOTES

Specifications subject to change without notice.

 $<sup>^1</sup>Temperature$  ranges are as follows: B Version: –40  $^{\circ}C$  to +85  $^{\circ}C.$ 

<sup>&</sup>lt;sup>2</sup>Guaranteed by design, not subject to production test.

**SPECIFICATIONS**<sup>1</sup> ( $V_{DD} = +3 \text{ V} \pm 10\%$ , GND = 0 V. All specifications  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  unless otherwise noted.)

	B Version				
		−40°C to			
Parameter	+25°C	+85°C	Units	Test Conditions/Comments	
ANALOG SWITCH					
Analog Signal Range		$0~\mathrm{V}$ to $\mathrm{V}_{\mathrm{DD}}$	V		
On-Resistance (R <sub>ON</sub> )	5	5.5	Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_S = -10 \text{ mA};$	
211 2100101111100 (14ON)		8	Ω max	Test Circuit 1	
On-Resistance Match Between	0.1	· ·	Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_S = -10 \text{ mA}$	
Channels ( $\Delta R_{ON}$ )	0.12	0.3	$\Omega$ max	, , , , , , , , , , , , , , , , , , ,	
On-Resistance Flatness (R <sub>FLAT(ON)</sub> )		2.5	Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_S = -10 \text{ mA}$	
LEAKAGE CURRENTS				$V_{DD} = +3.3 \text{ V};$	
Source OFF Leakage I <sub>S</sub> (OFF)	±0.01		nA typ	$V_{S} = 3 \text{ V/1 V}, V_{D} = 1 \text{ V/3 V};$	
Source Of T Leakage Is (OFT)	$\pm 0.01$	±0.2	nA typ	Test Circuit 2	
Drain OFF Leakage I <sub>D</sub> (OFF)	$\pm 0.1$ $\pm 0.01$	±0.2	nA typ	$V_S = 3 \text{ V/1 V}, V_D = 1 \text{ V/3 V};$	
Drain Orr Leakage ID (Orr)	$\pm 0.01$ $\pm 0.1$	±0.2	nA typ	Test Circuit 2	
Channel ON Leakage ID, IS (ON)	$\pm 0.1$ $\pm 0.01$	±0.2	nA typ	$V_S = V_D = 1 \text{ V, or } 3 \text{ V;}$	
Chamier Old Leakage 1D, 18 (Old)	$\pm 0.01$	±0.2	nA max	Test Circuit 3	
DIOUTAL DIDUTE			111111111111111111111111111111111111111	Tost Great 5	
DIGITAL INPUTS		2.0	<b>37</b> ·		
Input High Voltage, V <sub>INH</sub>		2.0	V min		
Input Low Voltage, V <sub>INL</sub>		0.4	V max		
Input Current	0.005		4	V - V - V	
I <sub>INL</sub> or I <sub>INH</sub>	0.005	±0.1	μA typ	$V_{IN} = V_{INL}$ or $V_{INH}$	
		±0.1	μA max		
DYNAMIC CHARACTERISTICS <sup>2</sup>					
$t_{ON}$	13		ns typ	$R_L = 300 \Omega, C_L = 35 pF,$	
	_	20	ns max	$V_S = 2 V$ ; Test Circuit 4	
$t_{ m OFF}$	7		ns typ	$R_L = 300 \Omega, C_L = 35 pF,$	
	_	12	ns max	$V_S = 2 \text{ V}$ ; Test Circuit 4	
Break-Before-Make Time Delay, t <sub>D</sub>	7	_	ns typ	$R_L = 300 \Omega, C_L = 35 pF,$	
(ADG713 Only)		1	ns min	$V_{S1} = V_{S2} = 2 \text{ V}$ ; Test Circuit 5	
Charge Injection	3		pC typ	$V_S = 1.5 \text{ V}; R_S = 0 \Omega, C_L = 1 \text{ nF};$ Test Circuit 6	
Off Isolation	-58		dB typ	$R_{L} = 50 \Omega, C_{L} = 5 pF, f = 10 MHz$	
	-78		dB typ	$R_L = 50 \Omega, C_L = 5 pF, f = 1 MHz;$	
				Test Circuit 7	
Channel-to-Channel Crosstalk	-90		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 10 MHz$ ; Test Circuit 8	
Bandwidth –3 dB	200		MHz typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ ; Test Circuit 9	
$C_{\rm S}$ (OFF)	10		pF typ	L 1111, IL 1 F1, 113t Should	
$C_{\rm D}$ (OFF)	10		pF typ		
$C_D, C_S(ON)$	22		pF typ		
POWER REQUIREMENTS				$V_{DD} = +3.3 \text{ V}$	
I <sub>DD</sub>	0.001		μA typ	Digital Inputs = 0 V or 3 V	
22		1.0	μA max		

NOTES <sup>1</sup>Temperature ranges are as follows: B Version: -40°C to +85°C.

<sup>&</sup>lt;sup>2</sup>Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

#### ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

$(T_A = +25^{\circ}C \text{ unless otherwise note})$	ed)
$V_{DD}$ to GND	0.3 V to +6 V
Analog, Digital Inputs <sup>2</sup>	$-0.3$ V to $V_{DD}$ +0.3 V or
	30 mA, Whichever Occurs First
Continuous Current, S or D .	30 mA
Peak Current, S or D	100 mA
(Pulse	d at 1 ms, 10% Duty Cycle max)
Operating Temperature Range	
Industrial (B Version)	40°C to +85°C
Storage Temperature Range .	–65°C to +150°C
Junction Temperature	+150°C
TSSOP Package, Power Dissipa	ation 430 mW
$\theta_{IA}$ Thermal Impedance	150°C/W

SOIC Package, Power Dissipation	
$\theta_{\rm IC}$ Thermal Impedance	
Lead Temperature, Soldering	
Vapor Phase (60 sec)+215°C	3
Infrared (15 sec)	3
ESD	7

#### NOTES

<sup>1</sup>Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

<sup>2</sup>Overvoltages at IN, S or D will be clamped by internal diodes. Current should be limited to the maximum ratings given.

#### CAUTION\_

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADG711/ADG712/ADG713 feature proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



#### **ORDERING GUIDE**

Model	Temperature Range	Package Description	Package Option
ADG711BR	−40°C to +85°C	0.15" Small Outline (SOIC)	R-16A
ADG712BR	−40°C to +85°C	0.15" Small Outline (SOIC)	R-16A
ADG713BR	−40°C to +85°C	0.15" Small Outline (SOIC)	R-16A
ADG711BRU	−40°C to +85°C	Thin Shrink Small Outline (TSSOP)	RU-16
ADG712BRU	−40°C to +85°C	Thin Shrink Small Outline (TSSOP)	RU-16
ADG713BRU	−40°C to +85°C	Thin Shrink Small Outline (TSSOP)	RU-16

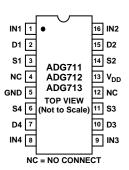
#### Table I. Truth Table (ADG711/ADG712)

ADG711 In	ADG712 In	Switch Condition
0	1	ON
1	0	OFF

#### Table II. Truth Table (ADG713)

Logic	Switch 1, 4	Switch 2, 3
0	OFF	ON
1	ON	OFF

## PIN CONFIGURATION (TSSOP/SOIC)



#### **TERMINOLOGY**

-			
$V_{\mathrm{DD}}$	Most positive power supply potential.	$t_{ m OFF}$	Delay between applying the digital control
GND	Ground (0 V) reference.		input and the output switching off.
S	Source terminal. May be an input or output.	$t_{\mathrm{D}}$	"OFF" time or "ON" time measured
D	Drain terminal. May be an input or output.		between the 90% points of both switches,
IN	Logic control input.		when switching from one address state to another. (ADG713 only).
$R_{ON}$	Ohmic resistance between D and S.	Crosstalk	A measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance.
$\Delta R_{\mathrm{ON}}$	On resistance match between any two channels i.e., $R_{\rm ON}$ max- $R_{\rm ON}$ min.	Crosstaik	
$R_{FLAT(ON)}$	Flatness is defined as the difference between the maximum and minimum value of on-	Off Isolation	A measure of unwanted signal coupling through an "OFF" switch.
	resistance as measured over the specified analog signal range.	Charge	A measure of the glitch impulse transferred
I <sub>S</sub> (OFF)	Source leakage current with the switch "OFF."	Injection	from the digital input to the analog output during switching.
$I_D$ (OFF)	Drain leakage current with the switch "OFF."	Bandwidth	The frequency at which the output is attenu-
$I_D, I_S (ON)$	Channel leakage current with the switch "ON."		ated by 3 dB.
$V_{D}(V_{S})$	Analog voltage on terminals D, S.	On Response	The frequency response of the "ON" switch.
$C_{S}$ (OFF)	"OFF" switch source capacitance.	On Loss	The voltage drop across the "ON" switch,
$C_D$ (OFF)	"OFF" switch drain capacitance.		seen on the On Response vs. Frequency plot
$C_D, C_S(ON)$	"ON" switch capacitance.		as how many dBs the signal is away from
$t_{ON}$	Delay between applying the digital control		0 dB at very low frequencies.
	input and the output switching on.		

## **Typical Performance Characteristics**

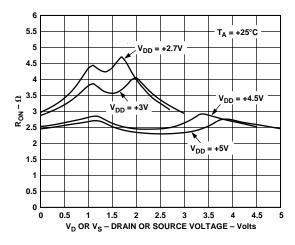


Figure 1. On Resistance as a Function of  $V_D$  ( $V_S$ )

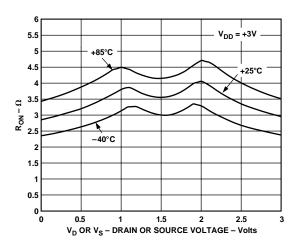


Figure 2. On Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures  $V_{DD}=3\ V$ 

## ADG711/ADG712/ADG713—Typical Performance Characteristics

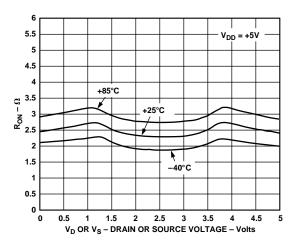


Figure 3. On Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures  $V_{DD} = 5 \ V$ 

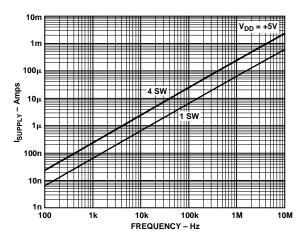


Figure 4. Supply Current vs. Input Switching Frequency

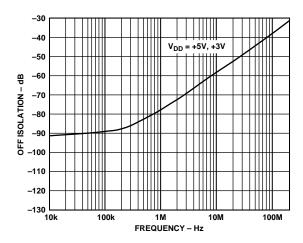


Figure 5. Off Isolation vs. Frequency

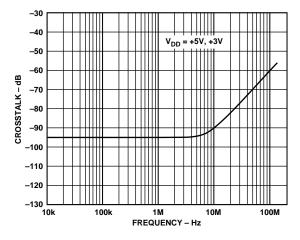


Figure 6. Crosstalk vs. Frequency

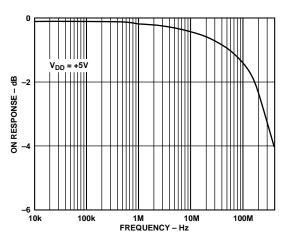


Figure 7. On Response vs. Frequency

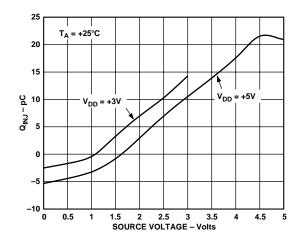


Figure 8. Charge Injection vs. Source Voltage

#### **APPLICATIONS**

Figure 9 illustrates a photodetector circuit with programmable gain. An AD820 is used as the output operational amplifier. With the resistor values shown in the circuit, and using different combinations of the switches, gain in the range of 2 to 16 can be achieved.

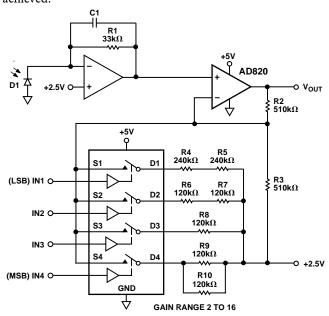
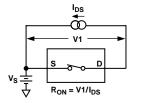


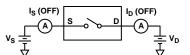
Figure 9. Photodetector Circuit with Programmable Gain

## **Test Circuits**



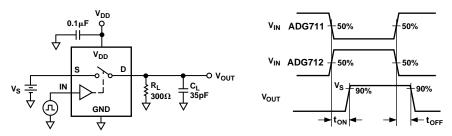
Test Circuit 1. On Resistance



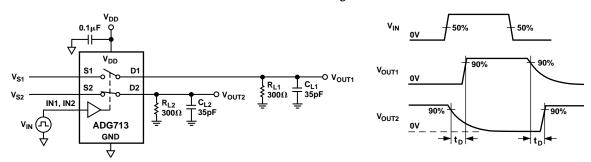


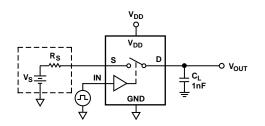
Test Circuit 2. Off Leakage

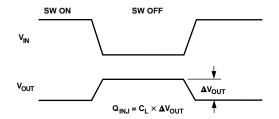
Test Circuit 3. On Leakage



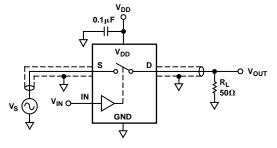
Test Circuit 4. Switching Times



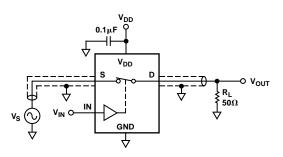




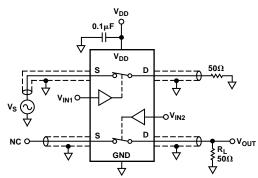
Test Circuit 6. Charge Injection



Test Circuit 7. Off Isolation



Test Circuit 9. Bandwidth

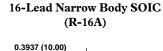


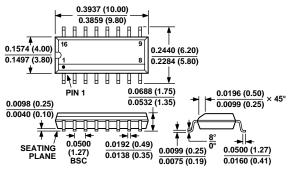
CHANNEL-TO-CHANNEL CROSSTALK =  $20 \times LOG |V_S/V_{OUT}|$ 

Test Circuit 8. Channel-to-Channel Crosstalk

#### **OUTLINE DIMENSIONS**

Dimensions shown in inches and (mm).





#### 16-Lead TSSOP (RU-16)

